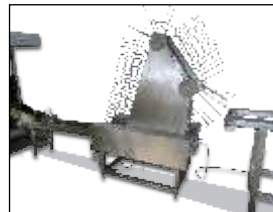
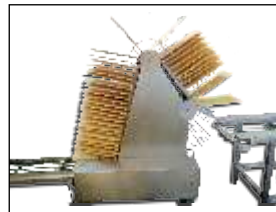
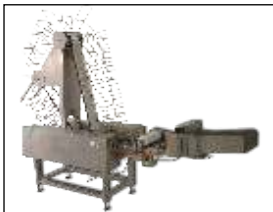
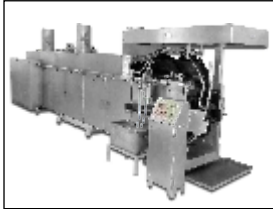




## Introducing the "Swift" compact wafer line.



### SWIFT 24

Capacity approx. 80-120 kg/hr

### SWIFT 36

Capacity approx. 120-160 kg/hr

The SWIFT wafer production plants comprise of the following single machines:

- Batter Mixer TM 3- 100 litre
- Automatic Wafer Baking Machine ZWA
- Wafer Sheet Cooler SC
- Automatic Wafer Creaming Machine CR
- Automatic Wafer Cutting Machine WC
- Conveyour C1 & C3

### Contents

# TECHNICAL

Hollow Wafers - New possibilities for speciality wafers



## **Hollow Wafers / Shaped Wafers**

Hollow Wafers opens new possibilities for increasing your market share.

It could also expand your premium range of products

What are your plans for the future?

We would love to hear from you.



# PRODUCT IDEAS

## INNOVATIVE PRODUCTS



## PHOTO FEATURES - Being closer to our clients



## FORTHCOMING EXHIBITIONS



**India**

Date: 31Jan.-3rd Feb., 2011  
Stall No.:B 18,  
Venue: Bombay Exhibition Centre,  
Mumbai India



**Mexico**

Date: 24th Feb.-26th Feb., 2011  
Stall No.:6021,  
Venue: Convention Centre,  
Guadalajara



**Dubai**

Date: 27 Feb - 2nd March, 2011  
Stall No.:S1-B78 in Sheikh Saeed  
Venue: Dubai International Convention  
and Exhibition Centre. Dubai

### BAKING OF WAFER SHEETS

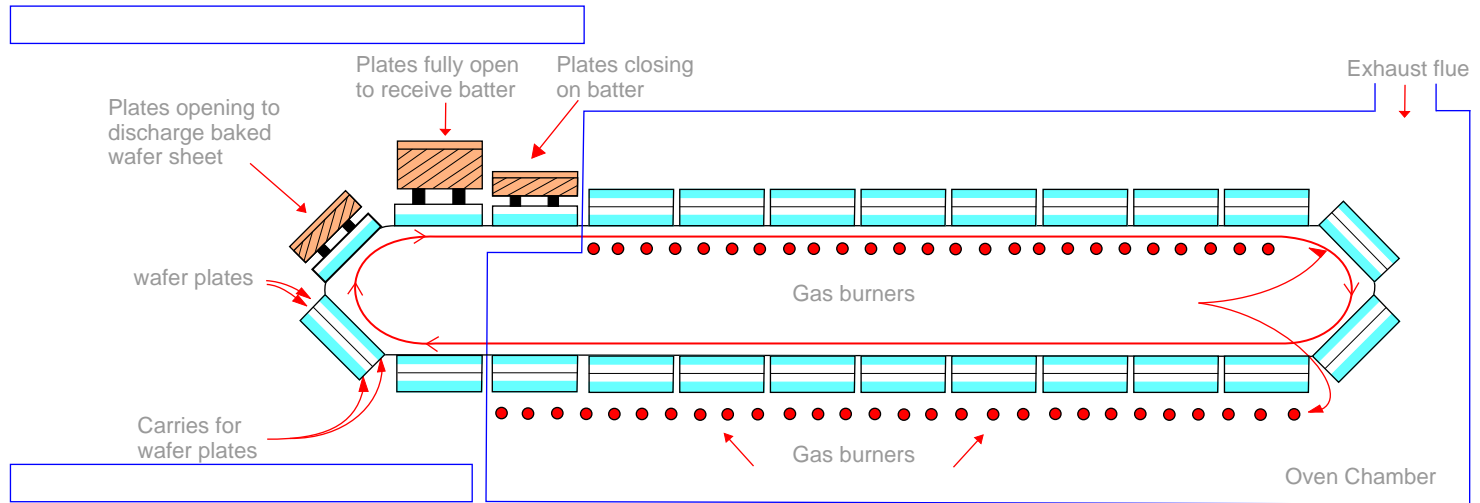


Diagram (not to scale) showing principles of construction of a 24 plate gas-fired wafer oven

The distance between the plates during baking is the primary factor affecting the thickness of the baked wafer sheet. Provision for adjustment of this distance is made in the method of mounting the plates. Again settings may vary with product but typical values lie in the range 1-2 mm.

A diagram of a gas-fired wafer oven is shown above. In the diagram 24 pairs of wafer plates are shown but ovens having up to 72 pairs of plates are not uncommon.

The plates are transported on a continuously moving conveyor through a heated tunnel but, unlike a biscuit oven, the batter is deposited and the baked product removed at the same end of the tunnel.



Heat is applied by gas flames (or in some cases by electric heaters) to the wafer plates during both forward and return traverses of the tunnel. The baking cycle commences with batter being deposited onto the lower of a pair of plates (batter depositing mechanism not shown). The upper plate is then lowered onto the bottom plate and the two plates are latched together.

This delay required an increase in the weight of batter deposited but gave a more uniform distribution of weight within the baked sheet. At the end of the baking cycle the wafer sheet is removed from the partly open wafer plates, frequently by means of a jet of compressed air.

The production of wafer sheet on a continuous basis has been achieved

(to be continued)

#### DISCLAIMER

We are unable to accept responsibility for any errors contained in this document, and we reserve the right to make changes.



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